

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A device for monitoring an electrolytic process, comprising at least one anode, ~~and~~ at least one cathode, ~~at least one a first~~ reference electrode being disposed at the surface of the at least one anode ~~or~~, ~~a second reference electrode being disposed~~ at the surface of the at least one cathode, ~~at least one and a~~ voltmeter being ~~respectively provided for detecting the electric voltages between the at least one anode and the at least one first reference electrode, a voltmeter provided between the first and the second reference electrodes, and a voltmeter provided between the second reference electrode and between the at least one reference electrode and the at least one cathode.~~
2. (Cancelled)
3. (Currently Amended) The device according to ~~one of the aforementioned claims 1-2~~ claim 1, wherein the ~~at least one first and second~~ reference electrode communicates through capillaries with the surface of the at least one anode or with the surface of the at least one cathode.
4. (Currently Amended) The device according to claim 3, ~~wherein~~ means are provided by ~~means of which~~ electrolyte fluid is deliverable through the capillaries to the ~~at least one first and second~~ reference electrode.
5. (Currently Amended) The device according to ~~one of the aforementioned claims 1-2~~ claim 1, **wherein** the at least one anode and the at least one cathode are paralleled and oriented horizontally or tilted from horizontal.

6. (Currently Amended) The device according to ~~one of the aforementioned claims 1-2~~ claim 1, wherein the cathode is a wafer or a chip carrier substrate and the anode is a metal plate.

7. (Currently Amended) A method of monitoring an electrolytic process in an electrolytic cell comprised of at least one anode and of at least one cathode, ~~at least one a first reference electrode being disposed at the surface of the at least one anode or, a second reference electrode at the surface of the at least one cathode, at least one and a voltmeter being respectively provided for detecting the electric voltages between the at least one anode and the at least one first reference electrode, a voltmeter provided between the first and the second reference electrodes, and a voltmeter provided between the at least one second reference electrode and the at least one cathode,~~ said method involving the following method steps:

- a) disposing the first reference electrode at the surface of the at least one anode and disposing the second reference electrode at the surface of the at least one cathode;
- b) providing an electric current flow between the at least one anode and the at least one cathode,
- b) c) concurrently detecting and directly measuring with a voltmeter the respective electric voltages between the at least one anode and the at least one first reference electrode, between the first and second electrodes, and between the at least one second reference electrode and the at least one cathode.

8. (Cancelled)

9. (Currently Amended) The method according to ~~one of the claims 7 and 8~~ claim 7, wherein the ~~at least one first~~ reference electrode is brought into contact with the surface of the at least one anode ~~or and the second reference electrode is brought into contact~~ with the surface of the at least one cathode by way of capillaries.

10. (Currently Amended) The method according to claim 9, wherein electrolyte fluid is delivered through the capillaries to the ~~at least one~~ first and second reference electrode.
11. (Currently Amended) The method according to ~~one of the claims 7–8~~ claim 7, wherein the at least one anode and the at least one cathode are paralleled and oriented horizontally or titled from horizontal.
12. (Currently Amended) The method according to ~~one of the claims 7–8~~ claim 7, wherein the cathode is a wafer or a chip carrier substrate and wherein the anode is a metal plate and wherein the metal is electrolytically deposited on the wafer.
13. (New) The device according to claim 1, wherein the first reference electrode is located in immediate proximity to the at least one anode and the second reference electrode is located in immediate proximity to the at least one cathode.
14. (New) The device according to claim 1, wherein the first reference electrode and second reference electrode are stable reference electrodes.
15. (New) The method according to claim 7, wherein the first reference electrode and second reference electrode are stable reference electrodes.